

Claims: What is claimed is:

7. A computer system board with a plurality of shield expansion housing apparatuses
5 for add-on expansion daughter board comprises:

a computer system board with plurality of on PCB shield zone
a plurality of shield expansion housing cover

8. The on PCB shield zone of claim 7 is a ground shield copper plate PCB
10 area with solder able surrounding zone where the said shield expansion
housing cover can be solder on to.

9. The shield expansion housing cover of claim 7 is a metallic cover box with
an open base that can be solder on to the solder able surrounding zone of
15 claim 8.

10. An apparatus of conduct heat from high heat generate electronics on the said
expansion daughter board to shield expansion zone comprises:

a on PCB shield zone of claim 7
20 a expansion daughter board attached in to the connector/s within the said on
PCB shield zone
a metallic shield expansion housing cover soldered on the said on PCB
shield zone
plurality of heat conduct material mounted between and contact the daughter
25 and
the said on PCB shield zone and the inside of the said metallic shield
expansion housing cover
Heat conduct means on top of the said metallic shield expansion housing
cover

30